

Vishay Siliconix

P-Channel 12-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}$ (Ω)	$R_{DS(on)}(\Omega)$ $I_{D}(A)$		
- 12	$0.029 \text{ at V}_{GS} = -4.5 \text{ V}$	- 12 ^a		
	0.034 at V _{GS} = - 2.5 V	- 12 ^a	23 nC	
	0.044 at V _{GS} = - 1.8 V	- 12 ^a	23110	
	0.10 at V _{GS} = - 1.5 V	- 3		

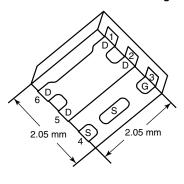
FEATURES

- · Halogen-free
- TrenchFET[®] Power MOSFET
- New Thermally Enhanced PowerPAK[®] SC-70 Package
 - Small Footprint Area
 - Low On-Resistance



RoHS

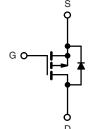
PowerPAK SC-70-6L-Single



Part # code BFX XXX Lot Traceability and Date code

APPLICATIONS

Load Switch, PA Switch and Battery Switch for Portable Devices



P-Channel MOSFET

Ordering Information:SiA413DJ-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	- 12	V	
Gate-Source Voltage		V_{GS}		
Continuous Drain Current (T _J = 150 °C)	$T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 70 ^{\circ}\text{C}$ $T_{A} = 25 ^{\circ}\text{C}$ $T_{A} = 70 ^{\circ}\text{C}$	I _D	- 12 ^a - 12 ^a - 10 ^{b, c} - 8 ^{b, c}	A
Pulsed Drain Current		I _{DM}	- 40	┤ ``
Continuous Source-Drain Diode Current	$T_C = 25 ^{\circ}\text{C}$ $T_A = 25 ^{\circ}\text{C}$	I _S	- 12 ^a - 2.9 ^{b, c}	
Maximum Power Dissipation	$T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 70 ^{\circ}\text{C}$ $T_{A} = 25 ^{\circ}\text{C}$ $T_{A} = 70 ^{\circ}\text{C}$	P _D	19 12 3.5 ^{b, c} 2.2 ^{b, c}	w
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 150	°C	
Soldering Recommendations (Peak Temperature	Ü	260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, f}	t ≤ 5 s	R_{thJA}	28	36	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	5.3	6.5	- 0/00	

Notes:

- a. Package limited.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. See Solder Profile (http://www.vishay.com/ppg?73257). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under Steady State conditions is 80 °C/W.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	,						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 12			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			- 11		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = -250 \mu A$		2.7			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.4		- 1	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current		V _{DS} = - 12 V, V _{GS} = 0 V			- 1		
	IDSS	V_{DS} = - 12 V, V_{GS} = 0 V, T_J = 55 °C			- 10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 20			Α	
Drain-Source On-State Resistance ^a	5(6.1)	$V_{GS} = -4.5 \text{ V}, I_D = -6.7 \text{ A}$		0.024	0.029		
	_	$V_{GS} = -2.5 \text{ V}, I_D = -6.2 \text{ A}$		0.028	0.034	Ω	
	R _{DS(on)}	$V_{GS} = -1.8 \text{ V}, I_D = -2.3 \text{ A}$		0.036	0.044		
		V _{GS} = - 1.5 V, I _D = - 1 A		0.050	0.100		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 6.7 A		30		S	
Dynamic ^b		-				l	
Input Capacitance	C _{iss}			1800		pF	
Output Capacitance	C _{oss}	V _{DS} = - 10 V, V _{GS} = 0 V, f = 1 MHz		450			
Reverse Transfer Capacitance	C _{rss}	20 40		390			
· · · · · · · · · · · · · · · · · · ·		V _{DS} = -6 V, V _{GS} = -8 V, I _D = -10 A		38	57	nC	
Total Gate Charge	Q_g	V _{DS} = -6 V, V _{GS} = -4.5 V, I _D = -10 A		23	35		
Gate-Source Charge	Q _{gs}			3			
Gate-Drain Charge	Q _{gd}			6.5			
Gate Resistance	R_g	f = 1 MHz		7		Ω	
Turn-On Delay Time	t _{d(on)}			20	30		
Rise Time	t _r	$V_{DD} = -6 \text{ V}, R_{L} = 0.75 \Omega$		40	60		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ - 8 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		65	100		
Fall Time	t _f			40	60		
Turn-On Delay Time	t _{d(on)}			10	15	ns	
Rise Time	t _r	V_{DD} = - 6 V, R_L = 0.75 Ω		12	20	1	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong -8 \text{ A}, V_{GEN} = -8 \text{ V}, R_g = 1 \Omega$		70	105		
Fall Time	t _f			40	60	1	
Drain-Source Body Diode Characterist	ics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 12		
Pulse Diode Forward Current	I _{SM}				40	- A	
Body Diode Voltage	V_{SD}	I _S = -8 A, V _{GS} = 0 V		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time t _{rr}				40	60	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	$I_F = -8 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s, T}_J = 25 ^{\circ}\text{C}$		20	30	nC	
Reverse Recovery Fall Time	t _a			14		ns	
Reverse Recovery Rise Time	t _b			26			

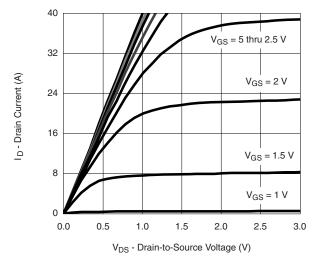
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

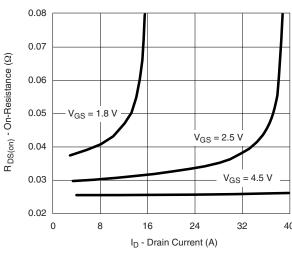


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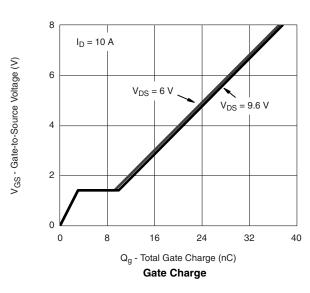
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

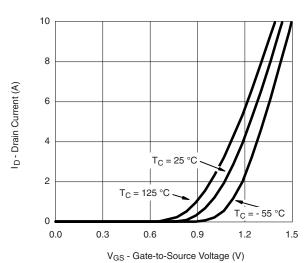


Output Characteristics

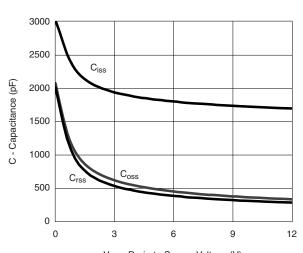


On-Resistance vs. Drain Current and Gate Voltage

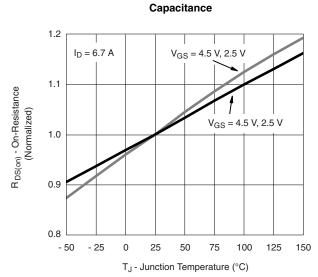




Transfer Characteristics



 $V_{\mbox{\footnotesize DS}}$ - Drain-to-Source Voltage (V)



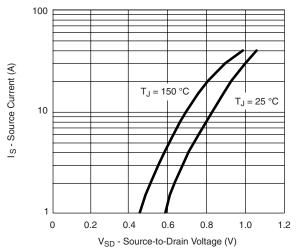
On-Resistance vs. Junction Temperature

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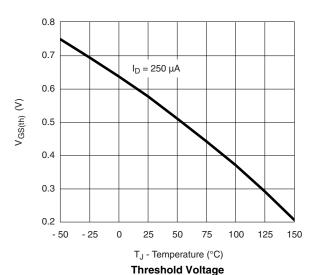
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Soure-Drain Diode Forward Voltage



0.060

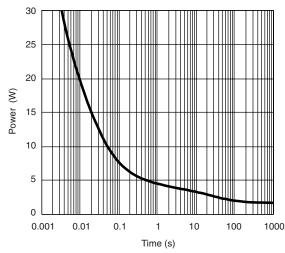
I_D = 6.7 A

T_A = 125 °C

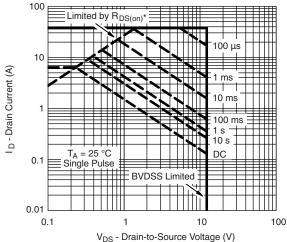
T_A = 25 °C

0.012

0 1 2 3 4 5



Single Pulse Power, Junction-to-Ambient



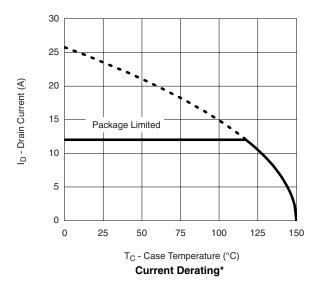
* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

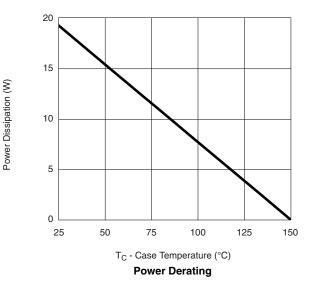
Safe Operating Area, Junction-to-Ambient



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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





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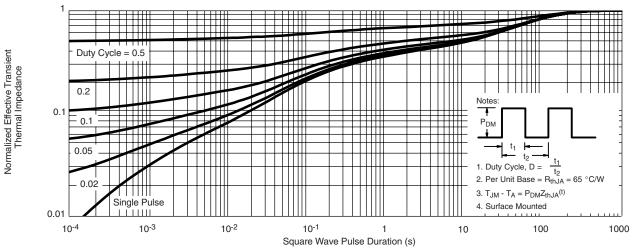
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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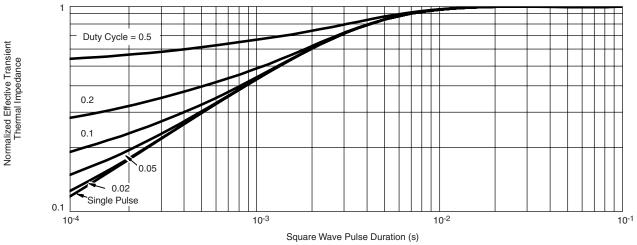
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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